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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	18480
Number of Logic Elements/Cells	49000
Total RAM Bits	3464192
Number of I/O	224
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-FBGA
Supplier Device Package	484-UBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5ceba4u19c8n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Cyclone V Device Overview

The Cyclone[®] V devices are designed to simultaneously accommodate the shrinking power consumption, cost, and time-to-market requirements; and the increasing bandwidth requirements for high-volume and cost-sensitive applications.

Enhanced with integrated transceivers and hard memory controllers, the Cyclone V devices are suitable for applications in the industrial, wireless and wireline, military, and automotive markets.

Related Information

Cyclone V Device Handbook: Known Issues Lists the planned updates to the Cyclone V Device Handbook chapters.

Key Advantages of Cyclone V Devices

Table 1. Key Advantages of the Cyclone V Device Family

Advantage	Supporting Feature
Lower power consumption	 Built on TSMC's 28 nm low-power (28LP) process technology and includes an abundance of hard intellectual property (IP) blocks Up to 40% lower power consumption than the previous generation device
Improved logic integration and differentiation capabilities	 8-input adaptive logic module (ALM) Up to 13.59 megabits (Mb) of embedded memory Variable-precision digital signal processing (DSP) blocks
Increased bandwidth capacity	3.125 gigabits per second (Gbps) and 6.144 Gbps transceiversHard memory controllers
Hard processor system (HPS) with integrated Arm* Cortex*-A9 MPCore* processor	 Tight integration of a dual-core Arm Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Cyclone V system-on-a-chip (SoC) Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric
Lowest system cost	 Requires only two core voltages to operate Available in low-cost wirebond packaging Includes innovative features such as Configuration via Protocol (CvP) and partial reconfiguration

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Feature	Description
	 HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller Arm CoreSight[™] JTAG debug access port, trace port, and on-chip trace storage
Configuration	 Tamper protection—comprehensive design protection to protect your valuable IP investments Enhanced advanced encryption standard (AES) design security features CvP Dynamic reconfiguration of the FPGA Active serial (AS) x1 and x4, passive serial (PS), JTAG, and fast passive parallel (FPP) x8 and x16 configuration options Internal scrubbing ⁽²⁾ Partial reconfiguration ⁽³⁾

Cyclone V Device Variants and Packages

Table 3. Device Variants for the Cyclone V Device Family

Variant	Description
Cyclone V E	Optimized for the lowest system cost and power requirement for a wide spectrum of general logic and DSP applications
Cyclone V GX	Optimized for the lowest cost and power requirement for 614 Mbps to 3.125 Gbps transceiver applications
Cyclone V GT	The FPGA industry's lowest cost and lowest power requirement for 6.144 Gbps transceiver applications
Cyclone V SE	SoC with integrated Arm-based HPS
Cyclone V SX	SoC with integrated Arm-based HPS and 3.125 Gbps transceivers
Cyclone V ST	SoC with integrated Arm-based HPS and 6.144 Gbps transceivers

Cyclone V E

This section provides the available options, maximum resource counts, and package plan for the Cyclone V E devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Product Selector Guide.

Related Information

Product Selector Guide

Provides the latest information about Intel products.

⁽²⁾ The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

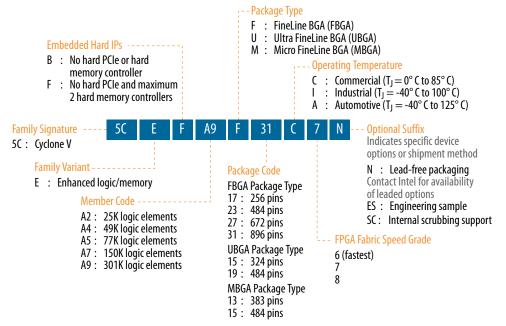
⁽³⁾ The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel[®] sales representatives.



Available Options

Figure 1. Sample Ordering Code and Available Options for Cyclone V E Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Maximum Resources

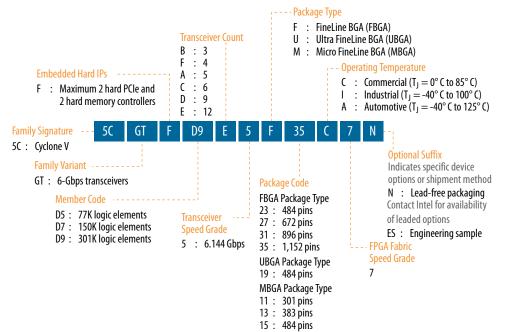
Table 4. Maximum Resource Counts for Cyclone V E Devices

Resource			Member Code					
		A2	A4	A5	A7	A9		
Logic Elements	(LE) (K)	25	49	77	150	301		
ALM		9,430	18,480	29,080	56,480	113,560		
Register		37,736	73,920	116,320	225,920	454,240		
Memory (Kb)	M10K	1,760	3,080	4,460	6,860	12,200		
	MLAB	196	303	424	836	1,717		
Variable-precision DSP Block		25	66	150	156	342		
18 x 18 Multipli	er	50	132	300	312	684		
PLL		4	4	6	7	8		
GPIO		224	224	240	480	480		
LVDS	Transmitter	56	56	60	120	120		
	Receiver	56	56	60	120	120		
Hard Memory C	ontroller	1	1	2	2	2		



Available Options

Figure 3. Sample Ordering Code and Available Options for Cyclone V GT Devices



Maximum Resources

Table 8. Maximum Resource Counts for Cyclone V GT Devices

Resource			Member Code				
		D5	D7	D9			
Logic Elements (LE) (К)	77	150	301			
ALM		29,080	56,480	113,560			
Register		116,320	225,920	454,240			
Memory (Kb)	M10K	4,460	6,860	12,200			
	MLAB	424	836	1,717			
Variable-precision DS	P Block	150	156	342			
18 x 18 Multiplier		300	312	684			
PLL		6	7	8			
6 Gbps Transceiver		6	9	12			
GPIO ⁽⁵⁾		336	480	560			
LVDS	Transmitter	84	120	140			
				continued			

⁽⁵⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.



Maximum Resources

Table 10. Maximum Resource Counts for Cyclone V SE Devices

Res	ource		Ме	mber Code	
		A2	A4	A5	A6
Logic Elements (LE) (K)	25	40	85	110
ALM		9,430	15,880	32,070	41,910
Register		37,736	60,376	128,300	166,036
Memory (Kb)	M10K	1,400	2,700	3,970	5,570
	MLAB	138	231	480	621
Variable-precisio	Variable-precision DSP Block		84	87	112
18 x 18 Multiplie	18 x 18 Multiplier		168	174	224
FPGA PLL	FPGA PLL		5	6	6
HPS PLL		3	3	3	3
FPGA GPIO		145	145	288	288
HPS I/O		181	181	181	181
LVDS	Transmitter	32	32	72	72
	Receiver	37	37	72	72
FPGA Hard Memo	PGA Hard Memory Controller		1	1	1
HPS Hard Memory Controller		1	1	1	1
Arm Cortex-A9 M	IPCore Processor	Single- or dual- core	Single- or dual- core	Single- or dual-core	Single- or dual-core

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices Provides the number of LVDS channels in each device package.

Package Plan

Table 11.Package Plan for Cyclone V SE Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U484 (19 mm)				F8 (31 i	
	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O
A2	66	151	145	181	_	_
A4	66	151	145	181	_	_
A5	66	151	145	181	288	181
A6	66	151	145	181	288	181





Cyclone V SX

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

Product Selector Guide

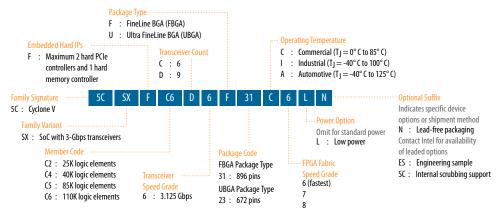
Provides the latest information about Intel products.

Available Options

Figure 5. Sample Ordering Code and Available Options for Cyclone V SX Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.



Maximum Resources

Table 12. Maximum Resource Counts for Cyclone V SX Devices

Reso	urce		Member Code					
		C2	C4	C5	C6			
Logic Elements (LE) (K)		25	40	85	110			
ALM		9,430	15,880	32,070	41,910			
Register		37,736	60,376	128,300	166,036			
Memory (Kb)	M10K	1,400	2,700	3,970	5,570			
	MLAB	138	231	480	621			
Variable-precision D	SP Block	36	84	87	112			
18 x 18 Multiplier		72	168	174	224			
FPGA PLL		5	5	6	6			
			•		continued.			

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Resource		Member Code				
		C2	C4	C5	C6	
HPS PLL		3	3	3	3	
3 Gbps Transce	iver	6	6	9	9	
FPGA GPIO ⁽⁸⁾		145	145	288	288	
HPS I/O		181	181	181	181	
LVDS	Transmitter	32	32	72	72	
	Receiver	37	37	72	72	
PCIe Hard IP Bl	lock	2	2	2 ⁽⁹⁾	2 (9)	
FPGA Hard Memory Controller		1	1	1	1	
HPS Hard Memory Controller		1	1	1	1	
Arm Cortex-A9	MPCore Processor	Dual-core	Dual-core	Dual-core	Dual-core	

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices Provides the number of LVDS channels in each device package.

Package Plan

Table 13.Package Plan for Cyclone V SX Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U672 (23 mm)		F896 (31 mm)			
	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR
C2	145	181	6	_	_	_
C4	145	181	6	_	_	_
C5	145	181	6	288	181	9
C6	145	181	6	288	181	9

Cyclone V ST

This section provides the available options, maximum resource counts, and package plan for the Cyclone V ST devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

⁽⁸⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

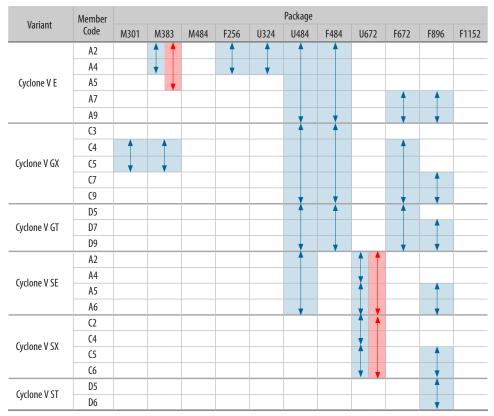
⁽⁹⁾ 1 PCIe Hard IP Block in U672 package.



I/O Vertical Migration for Cyclone V Devices

Figure 7. Vertical Migration Capability Across Cyclone V Device Packages and Densities

The arrows indicate the vertical migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



You can achieve the vertical migration shaded in red if you use only up to 175 GPIOs for the M383 package, and 138 GPIOs for the U672 package. These migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

Note: To verify the pin migration compatibility, use the Pin Migration View window in the Intel Quartus Prime software Pin Planner.

Adaptive Logic Module

Cyclone V devices use a 28 nm ALM as the basic building block of the logic fabric.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.



Table 16. Variable-Precision DSP Block Configurations for Cyclone V Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resource
Low precision fixed point for video applications	Three 9 x 9	1
Medium precision fixed point in FIR filters	Two 18 x 18	1
FIR filters and general DSP usage	Two 18 x 18 with accumulate	1
High precision fixed- or floating-point implementations	One 27 x 27 with accumulate	1

You can configure each DSP block during compilation as independent three 9 x 9, two 18×18 , or one 27×27 multipliers. With a dedicated 64 bit cascade bus, you can cascade multiple variable-precision DSP blocks to implement even higher precision DSP functions efficiently.

Table 17. Number of Multipliers in Cyclone V Devices

The table lists the variable-precision DSP resources by bit precision for each Cyclone V device.

Variant	Member Code	Variable- precision DSP Block		dent Input an plications Ope		18 x 18 Multiplier	18 x 18 Multiplier
		DSP Block	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	Adder Mode	Adder Summed with 36 bit Input
Cyclone V E	A2	25	75	50	25	25	25
	A4	66	198	132	66	66	66
-	A5	150	450	300	150	150	150
	A7	156	468	312	156	156	156
	A9	342	1,026	684	342	342	342
Cyclone V	C3	57	171	114	57	57	57
GX	C4	70	210	140	70	70	70
-	C5	150	450	300	150	150	150
	C7	156	468	312	156	156	156
	C9	342	1,026	684	342	342	342
Cyclone V GT	D5	150	450	300	150	150	150
	D7	156	468	312	156	156	156
-	D9	342	1,026	684	342	342	342
Cyclone V SE	A2	36	108	72	36	36	36
	A4	84	252	168	84	84	84
-	A5	87	261	174	87	87	87
	A6	112	336	224	112	112	112
Cyclone V SX	C2	36	108	72	36	36	36
-	C4	84	252	168	84	84	84
	C5	87	261	174	87	87	87
							continued



	Member	M10K		ML	Total RAM Bit	
Variant	Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	(Kb)
Cyclone V GT	D5	446	4,460	679	424	4,884
	D7	686	6,860	1338	836	7,696
	D9	1,220	12,200	2748	1,717	13,917
Cyclone V SE	A2	140	1,400	221	138	1,538
	A4	270	2,700	370	231	2,460
	A5	397	3,970	768	480	4,450
	A6	553	5,530	994	621	6,151
Cyclone V SX	C2	140	1,400	221	138	1,538
	C4	270	2,700	370	231	2,460
	C5	397	3,970	768	480	4,450
	C6	553	5,530	994	621	6,151
Cyclone V ST	D5	397	3,970	768	480	4,450
	D6	553	5,530	994	621	6,151

Embedded Memory Configurations

Table 19. Supported Embedded Memory Block Configurations for Cyclone V Devices

This table lists the maximum configurations supported for the embedded memory blocks. The information is applicable only to the single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MLAB	32	x16, x18, or x20
M10K	256	x40 or x32
	512	x20 or x16
	1К	x10 or x8
	2К	x5 or x4
	4К	x2
	8К	×1

Clock Networks and PLL Clock Sources

550 MHz Cyclone V devices have 16 global clock networks capable of up to operation. The clock network architecture is based on Intel's global, quadrant, and peripheral clock structure. This clock structure is supported by dedicated clock input pins and fractional PLLs.

Note: To reduce power consumption, the Intel Quartus Prime software identifies all unused sections of the clock network and powers them down.



PCIe Gen1 and Gen2 Hard IP

Cyclone V GX, GT, SX, and ST devices contain PCIe hard IP that is designed for performance and ease-of-use. The PCIe hard IP consists of the MAC, data link, and transaction layers.

The PCIe hard IP supports PCIe Gen2 and Gen1 end point and root port for up to x4 lane configuration. The PCIe Gen2 x4 support is PCIe-compatible.

The PCIe endpoint support includes multifunction support for up to eight functions, as shown in the following figure. The integrated multifunction support reduces the FPGA logic requirements by up to 20,000 LEs for PCIe designs that require multiple peripherals.

Figure 9. PCIe Multifunction for Cyclone V Devices



The Cyclone V PCIe hard IP operates independently from the core logic. This independent operation allows the PCIe link to wake up and complete link training in less than 100 ms while the Cyclone V device completes loading the programming file for the rest of the device.

In addition, the PCIe hard IP in the Cyclone V device provides improved end-to-end datapath protection using ECC.

External Memory Interface

This section provides an overview of the external memory interface in Cyclone V devices.

Hard and Soft Memory Controllers

Cyclone V devices support up to two hard memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices. Each controller supports 8 to 32 bit components of up to 4 gigabits (Gb) in density with two chip selects and optional ECC. For the Cyclone V SoC devices, an additional hard memory controller in the HPS supports DDR3, DDR2, and LPDDR2 SDRAM devices.

All Cyclone V devices support soft memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices for maximum flexibility.



External Memory Performance

Table 20. External Memory Interface Performance in Cyclone V Devices

The maximum and minimum operating frequencies depend on the memory interface standards and the supported delay-locked loop (DLL) frequency listed in the device datasheet.

Interface	Voltage	Maximum Free	Minimum Frequency	
	(V)	Hard Controller	Soft Controller	(MHz)
DDR3 SDRAM	1.5	400	303	303
	1.35	400	303	303
DDR2 SDRAM	1.8	400	300	167
LPDDR2 SDRAM	1.2	333	300	167

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

HPS External Memory Performance

Table 21. HPS External Memory Interface Performance

The hard processor system (HPS) is available in Cyclone V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	400
	1.35	400
DDR2 SDRAM	1.8	400
LPDDR2 SDRAM	1.2	333

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

Cyclone V devices deliver the industry's lowest power 6.144 Gbps transceivers at an estimated 88 mW maximum power consumption per channel. Cyclone V transceivers are designed to be compliant with a wide range of protocols and data rates.

Transceiver Channels

The transceivers are positioned on the left outer edge of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.



PCS Features

The Cyclone V core logic connects to the PCS through an 8, 10, 16, 20, 32, or 40 bit interface, depending on the transceiver data rate and protocol. Cyclone V devices contain PCS hard IP to support PCIe Gen1 and Gen2, Gbps Ethernet (GbE), Serial RapidIO[®] (SRIO), and Common Public Radio Interface (CPRI).

Most of the standard and proprietary protocols from 614 Mbps to 6.144 Gbps are supported.

Table 23.	Transceiver PCS	Features for C	vclone V Devices
		i cutui co i ci c	

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
3-Gbps and 6-Gbps Basic	0.614 to 6.144	 Phase compensation FIFO Byte serializer 8B/10B encoder Transmitter bit-slip 	 Word aligner Deskew FIFO Rate-match FIFO 8B/10B decoder Byte deserializer Byte ordering Receiver phase compensation FIFO
PCIe Gen1 (x1, x2, x4)	2.5 and 5.0	 Dedicated PCIe PHY IP core PIPE 2.0 interface to the core 	 Dedicated PCIe PHY IP core PIPE 2.0 interface to the core logic
PCIe Gen2 (x1, x2, x4) ⁽¹²⁾		logic	logic
GbE	1.25	 Custom PHY IP core with preset feature GbE transmitter synchronization state machine 	 Custom PHY IP core with preset feature GbE receiver synchronization state machine
XAUI (13)	3.125	Dedicated XAUI PHY IP core	Dedicated XAUI PHY IP core
HiGig	3.75	XAUI synchronization state machine for bonding four channels	XAUI synchronization state machine for realigning four channels
SRIO 1.3 and 2.1	1.25 to 3.125	 Custom PHY IP core with preset feature SRIO version 2.1-compliant x2 and x4 channel bonding 	 Custom PHY IP core with preset feature SRIO version 2.1-compliant x2 and x4 deskew state machine
SDI, SD/HD, and 3G-SDI	0.27 ⁽¹⁴⁾ , 1.485, and 2.97	Custom PHY IP core with preset feature	Custom PHY IP core with preset feature
JESD204A	0.3125 ⁽¹⁵⁾ to 3.125		
	•	•	continued

⁽¹²⁾ PCIe Gen2 is supported for Cyclone V GT and ST devices. The PCIe Gen2 x4 support is PCIe-compatible.

- ⁽¹³⁾ XAUI is supported through the soft PCS.
- $^{(14)}$ The 0.27-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.
- ⁽¹⁵⁾ The 0.3125-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.





PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
Serial ATA Gen1 and Gen2	1.5 and 3.0	 Custom PHY IP core with preset feature Electrical idle 	 Custom PHY IP core with preset feature Signal detect Wider spread of asynchronous SSC
CPRI 4.1 ⁽¹⁶⁾	0.6144 to 6.144	Dedicated deterministic latency PHY IP core	Dedicated deterministic latency PHY IP core
OBSAI RP3	0.768 to 3.072	Transmitter (TX) manual bit-slip mode	Receiver (RX) deterministic latency state machine
V-by-One HS	Up to 3.75	Custom PHY IP core	Custom PHY IP core
DisplayPort 1.2 ⁽¹⁷⁾	1.62 and 2.7		Wider spread of asynchronous SSC

SoC with HPS

Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

The HPS consists of a dual-core Arm Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

⁽¹⁶⁾ High-voltage output mode (1000-BASE-CX) is not supported.

⁽¹⁷⁾ Pending characterization.



HPS-FPGA AXI Bridges

The HPS–FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA[®]) Advanced eXtensible Interface (AXI[™]) specifications, consist of the following bridges:

- FPGA-to-HPS AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows the HPS to issue transactions to slaves in the FPGA fabric. This bridge is primarily used for control and status register (CSR) accesses to peripherals in the FPGA fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS–FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon[®] Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features. The SDRAM controller subsystem supports DDR2, DDR3, or LPDDR2 devices up to 4 Gb in density operating at up to 400 MHz (800 Mbps data rate).

FPGA Configuration and Processor Booting

The FPGA fabric and HPS in the SoC are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power, or shut down the entire FPGA fabric to reduce total system power.

You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or
 partially reconfigure the FPGA fabric at any time under software control. The HPS
 can also configure other FPGAs on the board through the FPGA configuration
 controller.
- You can power up both the HPS and the FPGA fabric together, configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.



Note: Although the FPGA fabric and HPS are on separate power domains, the HPS must remain powered up during operation while the FPGA fabric can be powered up or down as required.

Related Information

Cyclone V Device Family Pin Connection Guidelines

Provides detailed information about power supply pin connection guidelines and power regulator sharing.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer (Standard) system integration tool in the Intel Quartus Prime software.

For software development, the Arm-based SoC devices inherit the rich software development ecosystem available for the Arm Cortex-A9 MPCore processor. The software development process for Intel SoCs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux, VxWorks[®], and other operating systems is available for the SoCs. For more information on the operating systems support availability, contact the Intel sales team.

You can begin device-specific firmware and software development on the Intel SoC Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board that runs on a PC. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Related Information

International Altera Sales Support Offices

Dynamic and Partial Reconfiguration

The Cyclone V devices support dynamic reconfiguration and partial reconfiguration.

Dynamic Reconfiguration

The dynamic reconfiguration feature allows you to dynamically change the transceiver data rates, PMA settings, or protocols of a channel, without affecting data transfer on adjacent channels. This feature is ideal for applications that require on-the-fly multiprotocol or multirate support. You can reconfigure the PMA and PCS blocks with dynamic reconfiguration.

Partial Reconfiguration

Note: The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Partial reconfiguration allows you to reconfigure part of the device while other sections of the device remain operational. This capability is important in systems with critical uptime requirements because it allows you to make updates or adjust functionality without disrupting services.



Apart from lowering cost and power consumption, partial reconfiguration increases the effective logic density of the device because placing device functions that do not operate simultaneously is not necessary. Instead, you can store these functions in external memory and load them whenever the functions are required. This capability reduces the size of the device because it allows multiple applications on a single device—saving the board space and reducing the power consumption.

Intel simplifies the time-intensive task of partial reconfiguration by building this capability on top of the proven incremental compile and design flow in the Intel Quartus Prime design software. With the Intel solution, you do not need to know all the intricate device architecture details to perform a partial reconfiguration.

Partial reconfiguration is supported through the FPP x16 configuration interface. You can seamlessly use partial reconfiguration in tandem with dynamic reconfiguration to enable simultaneous partial reconfiguration of both the device core and transceivers.

Enhanced Configuration and Configuration via Protocol

Cyclone V devices support 1.8 V, 2.5 V, 3.0 V, and 3.3 V programming voltages and several configuration schemes.

Mode	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps)	Decompressi on	Design Security	Partial Reconfigurat ion ⁽¹⁸⁾	Remote System Update
AS through the EPCS and EPCQ serial configuration device	1 bit, 4 bits	100	_	Yes	Yes	_	Yes
PS through CPLD or external microcontroller	1 bit	125	125	Yes	Yes	_	_
FPP	8 bits	125	_	Yes	Yes	_	Parallel flash
	16 bits	125	_	Yes	Yes	Yes	loader
CvP (PCIe)	x1, x2, and x4 lanes	-	_	Yes	Yes	Yes	_
JTAG	1 bit	33	33	-	_	_	_

 Table 24.
 Configuration Schemes and Features Supported by Cyclone V Devices

Instead of using an external flash or ROM, you can configure the Cyclone V devices through PCIe using CvP. The CvP mode offers the fastest configuration rate and flexibility with the easy-to-use PCIe hard IP block interface. The Cyclone V CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

Related Information

Configuration via Protocol (CvP) Implementation in Intel FPGAs User Guide Provides more information about CvP.

⁽¹⁸⁾ The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Power Management

Leveraging the FPGA architectural features, process technology advancements, and transceivers that are designed for power efficiency, the Cyclone V devices consume less power than previous generation Cyclone FPGAs:

- Total device core power consumption—less by up to 40%.
- Transceiver channel power consumption—less by up to 50%.

Additionally, Cyclone V devices contain several hard IP blocks that reduce logic resources and deliver substantial power savings of up to 25% less power than equivalent soft implementations.

Document Revision History for Cyclone V Device Overview

Document Version	Changes
2018.05.07	 Added the low power option ("L" suffix) for Cyclone V SE and Cyclone V SX devices in the Sample Ordering Code and Available Options diagrams. Rebranded as Intel.

Date	Version	Changes
December 2017	2017.12.18	Updated ALM resources for Cyclone V E, Cyclone V SE, Cyclone V SX, and Cyclone V ST devices.
June 2016	2016.06.10	Updated Cyclone V GT speed grade to -7 in Sample Ordering Code and Available Options for Cyclone V GT Devices diagram.
December 2015	2015.12.21	 Added descriptions to package plan tables for Cyclone V GT and ST devices. Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.
June 2015	2015.06.12	 Replaced a note to partial reconfiguration feature. Note: The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Altera sales representatives. Updated logic elements (LE) (K) for the following devices: Cyclone V E A7: Updated from 149.5 to 150 Cyclone V GX C3: Updated from 149.7 to 150 Cyclone V GT D7: Updated from 149.5 to 150 Cyclone V GT D7: Updated from 149.5 to 150 Updated MLAB (Kb) in Maximum Resource Counts for Cyclone V GX Devices table as follows: Cyclone V GX C3: Updated from 291 to 182 Cyclone V GX C4: Updated from 678 to 424 Cyclone V GX C7: Updated from 1,338 to 836 Cyclone V GX C9: Updated from 1,717
	1	continued

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•Updated MLAB RAM Bit (KD) in Embedded Memory Capacity and Distribution in Cyclone V GX G3: Updated from 181 to 182 - Cyclone V GX G4: Updated from 25 to 243 • Updated Total RAM Bit (KD) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: - Cyclone V GX G3: Updated from 1,531 to 1,532 - Cyclone V GX G4: Updated from 2,795 to 2,924March 20152015.03.31• Added Internal Scrubbing Fedure under configuration in Summary of Fedures for Cyclone V Devices table as follows: - Cyclone V GX G4: Updated from 7,975 to 2,824 - Cyclone V GX G4: Updated from 7,975 to 2,824 - Cyclone V GX G4: Updated from 7,975 to 788 - Cyclone V GX G4: Updated from 797 to 678March 20152015.03.31• Added optional suffix "SC: Internal scrubbing fedure under configuration in Summary of Features for Cyclone V Devices table. - Added optional suffix "SC: Internal scrubbing fedure of VS Devices - Sample Ordering Code and Available Options for Cyclone V SE Devices - Sample Ordering Code and Available Options for Cyclone V ST Devices - Sample Ordering Code and Available Options for Cyclone V ST Devices - Sample Ordering Code and Available Options for Cyclone V ST Devices - Sample Ordering Code and Available Options for Cyclone V ST Devices - Sample Ordering Code and Available Options for Cyclone V ST Devices - Operating Temperature: Removed C and A temperature grades - Updated the transceiver specification for Cyclone V ST Devices - Operating Temperature: Removed C and A temperature grades - Updated Maximum Resource Counts for Cyclone V ST Devices - Device Variants for the Cyclone V Device Family table - Device Variants for the Cyclone V Device Family table - Device Variants for the Cyclone V Devices table for Cyclone V C Cyclone V GX G3 devices. - Logic elements (LF) (K): Updated from 51 to 57 	Date	Version	Changes
Features for Cyclone V Devices table.• Added optional suffix "SC: Internal scrubbing support" to the following diagrams:- Sample Ordering Code and Available Options for Cyclone V E Devices- Sample Ordering Code and Available Options for Cyclone V SX Devices- Sample Ordering Code and Available Options for Cyclone V SX Devices- Sample Ordering Code and Available Options for Cyclone V SX Devices- Sample Ordering Code and Available Options for Cyclone V SX Devices- Sample Ordering Code and Available Options for Cyclone V SX Devices- Sample Ordering Code and Available Options for Cyclone V STDevices figure because Cyclone V ST devices are only available in 1 temperature grade and -7 speed grade Operating Temperature: Removed C and A temperature grades- Updated the transceiver specification for Cyclone V ST Devices- Updated the transceiver specification for Cyclone V ST Devices- Updated the transceiver specification for Cyclone V ST Devices- Updated the transceiver counts for Cyclone V ST Devices- Updated Maximum Resource Counts for Cyclone V ST Devices- Logic elements (LE) (K): Updated from 51 to 57- 18 × 18 multiplier: Updated from 51 to 57- 9 × 9 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 134 bit Input: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 134 bit 17- 18 × 18 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier:			 Distribution in Cyclone V Devices table as follows: Cyclone V GX C3: Updated from 181 to 182 Cyclone V GX C4: Updated from 295 to 424 Updated Total RAM Bit (Kb) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: Cyclone V GX C3: Updated from 1,531 to 1,532 Cyclone V GX C4: Updated from 2,795 to 2,924 Updated MLAB Block count in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: Cyclone V GX C4: Updated from 2,795 to 2,924 Updated MLAB Block count in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: Cyclone V GX C4: Updated from 472 to 678
Devices figure because Cyclone V ST devices are only available in 1 temperature grade and -7 speed grade. 	March 2015	2015.03.31	 Features for Cyclone V Devices table. Added optional suffix "SC: Internal scrubbing support" to the following diagrams: Sample Ordering Code and Available Options for Cyclone V E Devices Sample Ordering Code and Available Options for Cyclone V GX Devices Sample Ordering Code and Available Options for Cyclone V SE Devices
	January 2015	2015.01.23	 Devices figure because Cyclone V ST devices are only available in I temperature grade and -7 speed grade. Operating Temperature: Removed C and A temperature grades FPGA Fabric Speed Grade: Removed -6 and -8 speed grades Updated the transceiver specification for Cyclone V ST from 5 Gbps to 6.144 Gbps: Device Variants for the Cyclone V Device Family table Sample Ordering Code and Available Options for Cyclone V ST Devices figure Maximum Resource Counts for Cyclone V ST Devices Updated Maximum Resource Counts for Cyclone V GX Devices table for Cyclone V GX G3 devices. Logic elements (LE) (K): Updated from 35.7 to 35.5 Variable-precision DSP block: Updated from 51 to 57 18 × 18 multiplier: Updated from 102 to 114 Updated Number of Multipliers in Cyclone V Devices table for Cyclone V GX G3 devices. Variableprecision DSP Block: Updated from 51 to 57 9 × 9 Multiplier: Updated from 153 to 171 18 × 18 Multiplier: Updated from 102 to 114 27 × 27 Multiplier: Updated from 51 to 57 18 × 18 Multiplier Adder Mode: Updated from 51 to 57 18 × 18 Multiplier Adder Summed with 36 bit Input: Updated from 51 to 57 18 × 18 Multiplier Adder Summed with 36 bit Input: Updated from 51 to 57 M10K RAM bit (Kb): Updated from 1,190 to 1,350 MLAB block: Updated from 255 to 291 MLAB RAM bit (Kb): Updated from 159 to 181
	October 2014	2014.10.06	

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Date	Version	Changes
		 Updated Figure 1, Figure 2, Figure 3, Figure 4, Figure 5, Figure 6, and Figure 10. Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections. Text edits throughout the document.
February 2012	1.2	 Updated Table 1–2, Table 1–3, and Table 1–6. Updated "Cyclone V Family Plan" on page 1–4 and "Clock Networks and PLL Clock Sources" on page 1–15. Updated Figure 1–1 and Figure 1–6.
November 2011	1.1	 Updated Table 1–1, Table 1–2, Table 1–3, Table 1–4, Table 1–5, and Table 1–6. Updated Figure 1–4, Figure 1–5, Figure 1–6, Figure 1–7, and Figure 1–8. Updated "System Peripherals" on page 1–18, "HPS-FPGA AXI Bridges" on page 1–19, "HPS SDRAM Controller Subsystem" on page 1–19, "FPGA Configuration and Processor Booting" on page 1–19, and "Hardware and Software Development" on page 1–20. Minor text edits.
October 2011	1.0	Initial release.